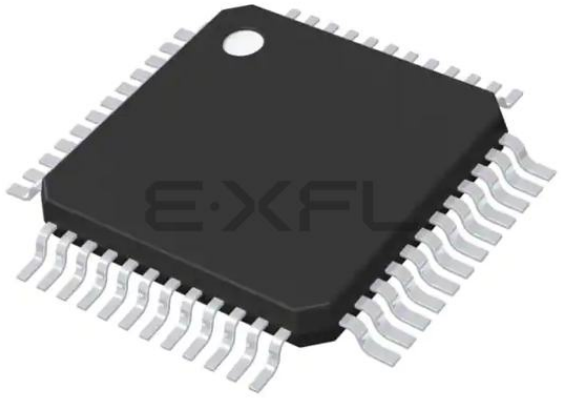
Infineon Technologies - SAF-XC886CM-6FFI 5V AC Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	XC800
Core Size	8-Bit
Speed	24MHz
Connectivity	CANbus, SSI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	34
Program Memory Size	24KB (24K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	1.75K x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 8x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	PG-TQFP-48
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc886cm-6ffi-5v-ac

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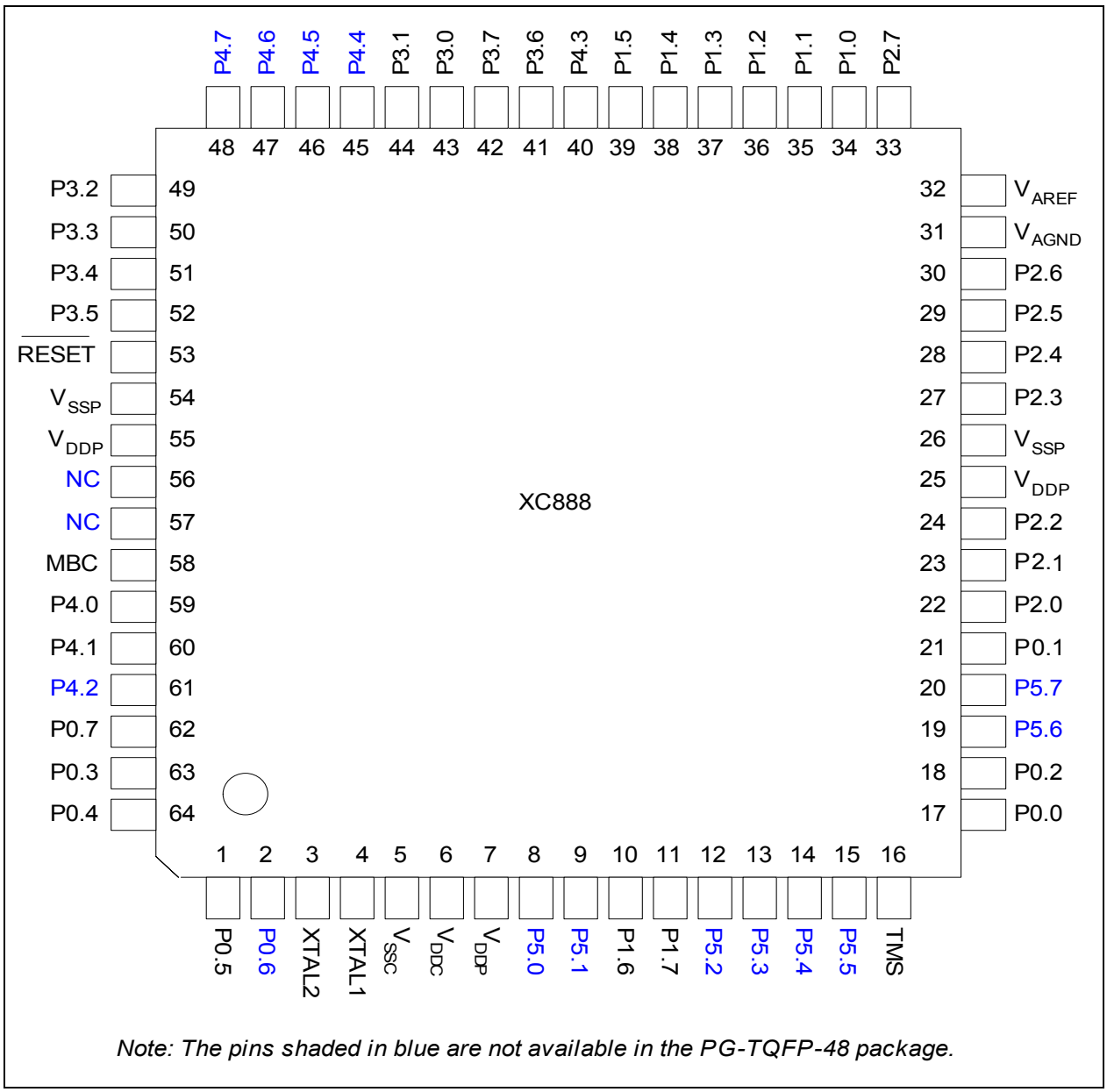


Note: The pins shaded in blue are not available in the PG-TQFP-48 package.

Figure 5 XC888 Pin Configuration, PG-TQFP-64 Package (top view)

SYSCON0
System Control Register 0 **Reset Value: 04_H**

7	6	5	4	3	2	1	0
	0		**IMODE**	**0**	**1**	**0**	**RMAP**
	r		rw	r	r	r	rw

Field	Bits	Type	Description
RMAP	0	rw	**Interrupt Node XINTR0 Enable** 0 The access to the standard SFR area is enabled 1 The access to the mapped SFR area is enabled
1	2	r	**Reserved** Returns 1 if read; should be written with 1.
0	[7:5], 3,1	r	**Reserved** Returns 0 if read; should be written with 0.

Note: The RMAP bit should be cleared/set by ANL or ORL instructions.

3.2.2.2 Address Extension by Paging

Address extension is further performed at the module level by paging. With the address extension by mapping, the XC886/888 has a 256-SFR address range. However, this is still less than the total number of SFRs needed by the on-chip peripherals. To meet this requirement, some peripherals have a built-in local address extension mechanism for increasing the number of addressable SFRs. The extended address range is not directly controlled by the CPU instruction itself, but is derived from bit field PAGE in the module page register MOD_PAGE. Hence, the bit field PAGE must be programmed before accessing the SFR of the target module. Each module may contain a different number of pages and a different number of SFRs per page, depending on the specific requirement. Besides setting the correct RMAP bit value to select the SFR area, the user must also ensure that a valid PAGE is selected to target the desired SFR. A page inside the extended address range can be selected as shown in **Figure 9**.

Table 13 T21 Register Overview (cont'd)

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
$C5_H$	**T21_T2H** **Reset: 00_H** Timer 2 Register High	Bit Field	THL2							
		Type	rwh							

3.2.4.10 CCU6 Registers

The CCU6 SFRs can be accessed in the standard memory area (RMAP = 0).

Table 14 CCU6 Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$A3_H$	**CCU6_PAGE** **Reset: 00_H** Page Register	Bit Field	OP		STNR		0	PAGE		
		Type	w		w		r	rw		
RMAP = 0, PAGE 0										
$9A_H$	**CCU6_CC63SRL** **Reset: 00_H** Capture/Compare Shadow Register for Channel CC63 Low	Bit Field	CC63SL							
		Type	rw							
$9B_H$	**CCU6_CC63SRH** **Reset: 00_H** Capture/Compare Shadow Register for Channel CC63 High	Bit Field	CC63SH							
		Type	rw							
$9C_H$	**CCU6_TCTR4L** **Reset: 00_H** Timer Control Register 4 Low	Bit Field	T12 STD	T12 STR	0		DT RES	T12 RES	T12R S	T12R R
		Type	w	w	r		w	w	w	w
$9D_H$	**CCU6_TCTR4H** **Reset: 00_H** Timer Control Register 4 High	Bit Field	T13 STD	T13 STR	0			T13 RES	T13R S	T13R R
		Type	w	w	r			w	w	w
$9E_H$	**CCU6_MCMOUTSL** **Reset: 00_H** Multi-Channel Mode Output Shadow Register Low	Bit Field	STRM CM	0	MCMPS					
		Type	w	r	rw					
$9F_H$	**CCU6_MCMOUTSH** **Reset: 00_H** Multi-Channel Mode Output Shadow Register High	Bit Field	STRH P	0	CURHS			EXPHS		
		Type	w	r	rw			rw		
$A4_H$	**CCU6_ISRL** **Reset: 00_H** Capture/Compare Interrupt Status Reset Register Low	Bit Field	RT12 PM	RT12 OM	RCC6 2F	RCC6 2R	RCC6 1F	RCC6 1R	RCC6 0F	RCC6 0R
		Type	w	w	w	w	w	w	w	w
$A5_H$	**CCU6_ISRH** **Reset: 00_H** Capture/Compare Interrupt Status Reset Register High	Bit Field	RSTR	RIDLE	RWH E	RCHE	0	RTRP F	RT13 PM	RT13 CM
		Type	w	w	w	w	r	w	w	w
$A6_H$	**CCU6_CMPMODIFL** **Reset: 00_H** Compare State Modification Register Low	Bit Field	0	MCC6 3S	0			MCC6 2S	MCC6 1S	MCC6 0S
		Type	r	w	r			w	w	w
$A7_H$	**CCU6_CMPMODIFH** **Reset: 00_H** Compare State Modification Register High	Bit Field	0	MCC6 3R	0			MCC6 2R	MCC6 1R	MCC6 0R
		Type	r	w	r			w	w	w

3.2.4.12 SSC Registers

The SSC SFRs can be accessed in the standard memory area (RMAP = 0).

Table 16 SSC Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$A9_H$	**SSC_PISEL** **Reset: 00_H** Port Input Select Register	Bit Field	0					CIS	SIS	MIS
		Type	r					rw	rw	rw
AA_H	**SSC_CONL** **Reset: 00_H** Control Register Low Programming Mode	Bit Field	LB	PO	PH	HB	BM			
		Type	rw	rw	rw	rw	rw			
AA_H	**SSC_CONL** **Reset: 00_H** Control Register Low Operating Mode	Bit Field	0				BC			
		Type	r				rh			
AB_H	**SSC_CONH** **Reset: 00_H** Control Register High Programming Mode	Bit Field	EN	MS	0	AREN	BEN	PEN	REN	TEN
		Type	rw	rw	r	rw	rw	rw	rw	rw
AB_H	**SSC_CONH** **Reset: 00_H** Control Register High Operating Mode	Bit Field	EN	MS	0	BSY	BE	PE	RE	TE
		Type	rw	rw	r	rh	rwh	rwh	rwh	rwh
AC_H	**SSC_TBL** **Reset: 00_H** Transmitter Buffer Register Low	Bit Field	TB_VALUE							
		Type	rw							
AD_H	**SSC_RBL** **Reset: 00_H** Receiver Buffer Register Low	Bit Field	RB_VALUE							
		Type	rh							
AE_H	**SSC_BRL** **Reset: 00_H** Baud Rate Timer Reload Register Low	Bit Field	BR_VALUE							
		Type	rw							
AF_H	**SSC_BRH** **Reset: 00_H** Baud Rate Timer Reload Register High	Bit Field	BR_VALUE							
		Type	rw							

3.2.4.13 MultiCAN Registers

The MultiCAN SFRs can be accessed in the standard memory area (RMAP = 0).

Table 17 CAN Register Overview

Addr	Register Name	Bit	7	6	5	4	3	2	1	0
RMAP = 0										
$D8_H$	**ADCON** **Reset: 00_H** CAN Address/Data Control Register	Bit Field	V3	V2	V1	V0	AUAD		BSY	RWEN
		Type	rw	rw	rw	rw	rw		rh	rw
$D9_H$	**ADL** **Reset: 00_H** CAN Address Register Low	Bit Field	CA9	CA8	CA7	CA6	CA5	CA4	CA3	CA2
		Type	rwh	rwh	rwh	rwh	rwh	rwh	rwh	rwh
DA_H	**ADH** **Reset: 00_H** CAN Address Register High	Bit Field	0				CA13	CA12	CA11	CA10
		Type	r				rwh	rwh	rwh	rwh

3.3 Flash Memory

The Flash memory provides an embedded user-programmable non-volatile memory, allowing fast and reliable storage of user code and data. It is operated from a single 2.5 V supply from the Embedded Voltage Regulator (EVR) and does not require additional programming or erasing voltage. The sectorization of the Flash memory allows each sector to be erased independently.

Features

- In-System Programming (ISP) via UART
- In-Application Programming (IAP)
- Error Correction Code (ECC) for dynamic correction of single-bit errors
- Background program and erase operations for CPU load minimization
- Support for aborting erase operation
- Minimum program width[1] of 32-byte for D-Flash and 64-byte for P-Flash
- 1-sector minimum erase width
- 1-byte read access
- Flash is delivered in erased state (read all zeros)
- Operating supply voltage: 2.5 V ± 7.5 %
- Read access time: 3 × t_{CCLK} = 125 ns[2]
- Program time: 248256 / f_{SYS} = 2.6 ms[3]
- Erase time: 9807360 / f_{SYS} = 102 ms[3]

1) P-Flash: 64-byte wordline can only be programmed once, i.e., one gate disturb allowed.
D-Flash: 32-byte wordline can be programmed twice, i.e., two gate disturbs allowed.

2) Values shown here are typical values. f_{sys} = 96 MHz ± 7.5% (f_{CCLK} = 24 MHz ± 7.5 %) is the maximum frequency range for Flash read access.

3) Values shown here are typical values. f_{sys} = 96 MHz ± 7.5% is the only frequency range for Flash programming and erasing. f_{sysmin} is used for obtaining the worst case timing.

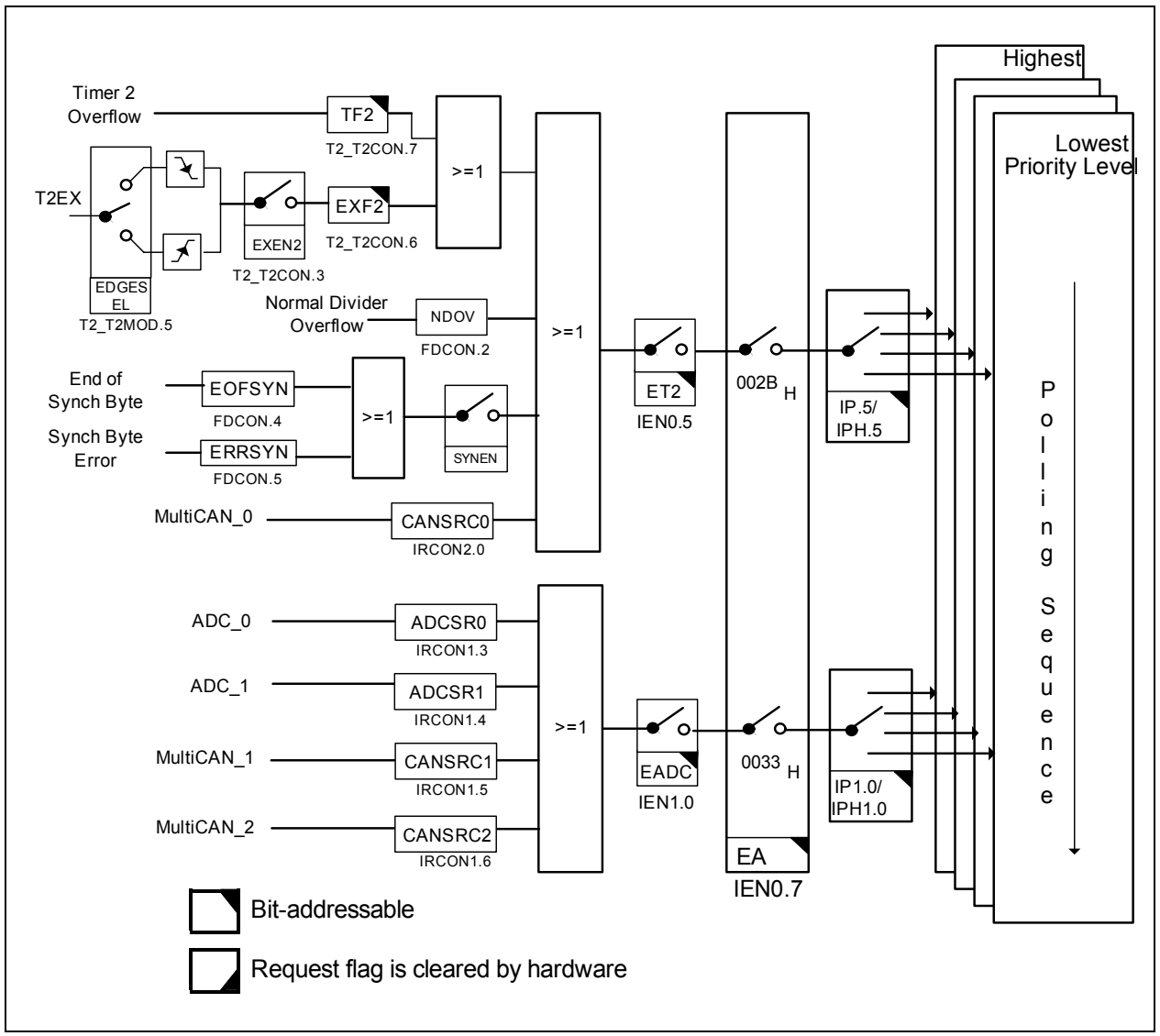


Figure 15 Interrupt Request Sources (Part 2)

3.7 Reset Control

The XC886/888 has five types of reset: power-on reset, hardware reset, watchdog timer reset, power-down wake-up reset, and brownout reset.

When the XC886/888 is first powered up, the status of certain pins (see **Table 23**) must be defined to ensure proper start operation of the device. At the end of a reset sequence, the sampled values are latched to select the desired boot option, which cannot be modified until the next power-on reset or hardware reset. This guarantees stable conditions during the normal operation of the device.

In order to power up the system properly, the external reset pin $\overline{\text{RESET}}$ must be asserted until V_{DDC} reaches 0.9*V_{DDC}. The delay of external reset can be realized by an external capacitor at $\overline{\text{RESET}}$ pin. This capacitor value must be selected so that V_{RESET} reaches 0.4 V, but not before V_{DDC} reaches 0.9* $V_{DDC.}$

A typical application example is shown in **Figure 22**. The V_{DDP} capacitor value is 100 nF while the V_{DDC} capacitor value is 220 nF. The capacitor connected to $\overline{\text{RESET}}$ pin is 100 nF.

Typically, the time taken for V_{DDC} to reach 0.9*V_{DDC} is less than 50 µs once V_{DDP} reaches 2.3V. Hence, based on the condition that 10% to 90% V_{DDP} (slew rate) is less than 500 µs, the $\overline{\text{RESET}}$ pin should be held low for 500 µs typically. See **Figure 23**.

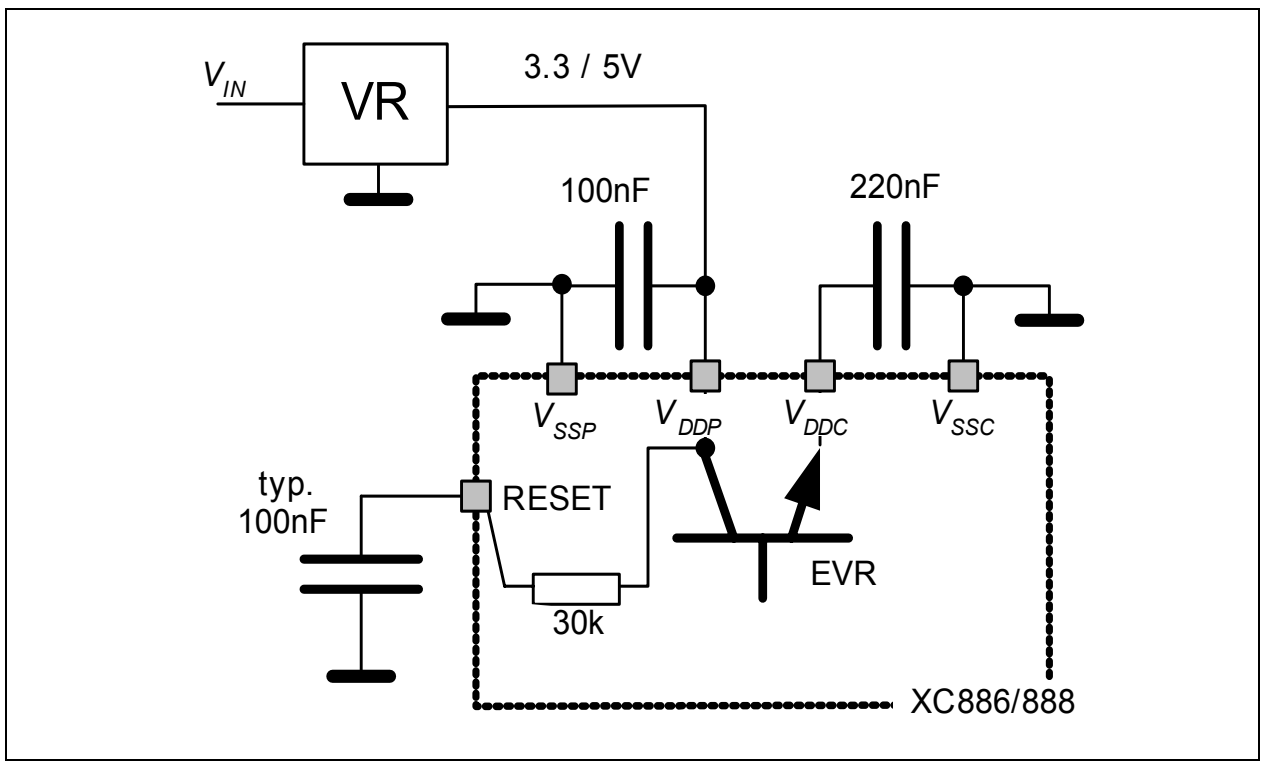


Figure 22 Reset Circuitry

Table 25 shows the VCO range for the XC886/888.

Table 25 VCO Range

f_{VCOmin}	f_{VCOmax}	$f_{VCOFREEmin}$	$f_{VCOFREEmax}$	Unit
150	200	20	80	MHz
100	150	10	80	MHz

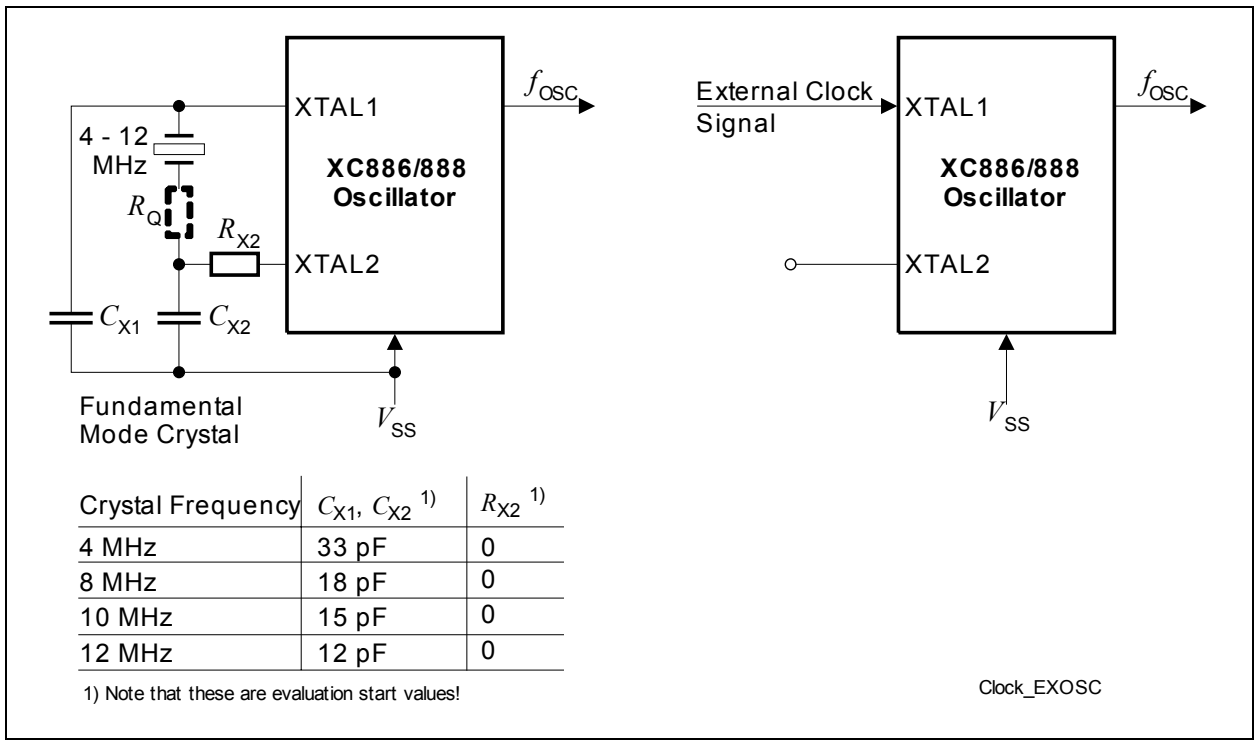
3.8.1 Recommended External Oscillator Circuits

The oscillator circuit, a Pierce oscillator, is designed to work with both, an external crystal oscillator or an external stable clock source. It basically consists of an inverting amplifier and a feedback element with XTAL1 as input, and XTAL2 as output.

When using a crystal, a proper external oscillator circuitry must be connected to both pins, XTAL1 and XTAL2. The crystal frequency can be within the range of 4 MHz to 12 MHz. Additionally, it is necessary to have two load capacitances C_{X1} and C_{X2}, and depending on the crystal type, a series resistor R_{X2}, to limit the current. A test resistor R_Q may be temporarily inserted to measure the oscillation allowance (negative resistance) of the oscillator circuitry. R_Q values are typically specified by the crystal vendor. The C_{X1} and C_{X2} values shown in Figure 25 can be used as starting points for the negative resistance evaluation and for non-productive systems. The exact values and related operating range are dependent on the crystal frequency and have to be determined and optimized together with the crystal vendor using the negative resistance method. Oscillation measurement with the final target system is strongly recommended to verify the input amplitude at XTAL1 and to determine the actual oscillation allowance (margin negative resistance) for the oscillator-crystal system.

When using an external clock signal, the signal must be connected to XTAL1. XTAL2 is left open (unconnected).

The oscillator can also be used in combination with a ceramic resonator. The final circuitry must also be verified by the resonator vendor. Figure 25 shows the recommended external oscillator circuitries for both operating modes, external crystal mode and external input clock mode.



Crystal Frequency	C_{X1}, C_{X2} 1)	R_{X2} 1)
4 MHz	33 pF	0
8 MHz	18 pF	0
10 MHz	15 pF	0
12 MHz	12 pF	0

1) Note that these are evaluation start values!

Figure 25 External Oscillator Circuitry

Note: For crystal operation, it is strongly recommended to measure the negative resistance in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the minimum and maximum values of the negative resistance specified by the crystal supplier.

For power saving purposes, the clocks may be disabled or slowed down according to Table 26.

Table 26 System frequency (f_{sys} = 96 MHz)

Power Saving Mode	Action
Idle	Clock to the CPU is disabled.
Slow-down	Clocks to the CPU and all the peripherals are divided by a common programmable factor defined by bit field CMCON.CLKREL.
Power-down	Oscillator and PLL are switched off.

3.18 Timer 2 and Timer 21

Timer 2 and Timer 21 are 16-bit general purpose timers (THL2) that are fully compatible and have two modes of operation, a 16-bit auto-reload mode and a 16-bit one channel capture mode, see **Table 33**. As a timer, the timers count with an input clock of PCLK/12 (if prescaler is disabled). As a counter, they count 1-to-0 transitions on pin T2. In the counter mode, the maximum resolution for the count is PCLK/24 (if prescaler is disabled).

Table 33 Timer 2 Modes

Mode	Description
Auto-reload	**Up/Down Count Disabled** • Count up only • Start counting from 16-bit reload value, overflow at $FFFF_H$ • Reload event configurable for trigger by overflow condition only, or by negative/positive edge at input pin T2EX as well • Programmble reload value in register RC2 • Interrupt is generated with reload event
	Up/Down Count Enabled • Count up or down, direction determined by level at input pin T2EX • No interrupt is generated • Count up – Start counting from 16-bit reload value, overflow at $FFFF_H$ – Reload event triggered by overflow condition – Programmble reload value in register RC2 • Count down – Start counting from $FFFF_H$, underflow at value defined in register RC2 – Reload event triggered by underflow condition – Reload value fixed at $FFFF_H$
Channel capture	• Count up only • Start counting from 0000_H, overflow at $FFFF_H$ • Reload event triggered by overflow condition • Reload value fixed at 0000_H • Capture event triggered by falling/rising edge at pin T2EX • Captured timer value stored in register RC2 • Interrupt is generated with reload or capture event

3.21 Analog-to-Digital Converter

The XC886/888 includes a high-performance 10-bit Analog-to-Digital Converter (ADC) with eight multiplexed analog input channels. The ADC uses a successive approximation technique to convert the analog voltage levels from up to eight different sources. The analog input channels of the ADC are available at Port 2.

Features

- Successive approximation
- 8-bit or 10-bit resolution
  (TUE of ± 1 LSB and ± 2 LSB, respectively)
- Eight analog channels
- Four independent result registers
- Result data protection for slow CPU access
  (wait-for-read mode)
- Single conversion mode
- Autoscan functionality
- Limit checking for conversion results
- Data reduction filter
  (accumulation of up to 2 conversion results)
- Two independent conversion request sources with programmable priority
- Selectable conversion request trigger
- Flexible interrupt generation with configurable service nodes
- Programmable sample time
- Programmable clock divider
- Cancel/restart feature for running conversions
- Integrated sample and hold circuitry
- Compensation of offset errors
- Low power modes

3.21.1 ADC Clocking Scheme

A common module clock f_{ADC} generates the various clock signals used by the analog and digital parts of the ADC module:

- f_{ADCA} is input clock for the analog part.
- f_{ADCI} is internal clock for the analog part (defines the time base for conversion length and the sample time). This clock is generated internally in the analog part, based on the input clock f_{ADCA} to generate a correct duty cycle for the analog components.
- f_{ADCD} is input clock for the digital part.

The internal clock for the analog part f_{ADCI} is limited to a maximum frequency of 10 MHz. Therefore, the ADC clock prescaler must be programmed to a value that ensures f_{ADCI} does not exceed 10 MHz. The prescaler ratio is selected by bit field CTC in register

3.22 On-Chip Debug Support

The On-Chip Debug Support (OCDS) provides the basic functionality required for the software development and debugging of XC800-based systems.

The OCDS design is based on these principles:

- Use the built-in debug functionality of the XC800 Core
- Add a minimum of hardware overhead
- Provide support for most of the operations by a Monitor Program
- Use standard interfaces to communicate with the Host (a Debugger)

Features

- Set breakpoints on instruction address and on address range within the Program Memory
- Set breakpoints on internal RAM address range
- Support unlimited software breakpoints in Flash/RAM code region
- Process external breaks via JTAG and upon activating a dedicated pin
- Step through the program code

The OCDS functional blocks are shown in **Figure 37**. The Monitor Mode Control (MMC) block at the center of OCDS system brings together control signals and supports the overall functionality. The MMC communicates with the XC800 Core, primarily via the Debug Interface, and also receives reset and clock signals.

After processing memory address and control signals from the core, the MMC provides proper access to the dedicated extra-memories: a Monitor ROM (holding the code) and a Monitor RAM (for work-data and Monitor-stack).

The OCDS system is accessed through the JTAG[1)], which is an interface dedicated exclusively for testing and debugging activities and is not normally used in an application. The dedicated MBC pin is used for external configuration and debugging control.

Note: All the debug functionality described here can normally be used only after XC886/888 has been started in OCDS mode.

1) The pins of the JTAG port can be assigned to either the primary port (Port 0) or either of the secondary ports (Ports 1 and 2/Port 5).
User must set the JTAG pins (TCK and TDI) as input during connection with the OCDS system.

4.2 DC Parameters

The electrical characteristics of the DC Parameters are detailed in this section.

4.2.1 Input/Output Characteristics

Table 38 provides the characteristics of the input/output pins of the XC886/888.

Table 38 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
V_{DDP} = 5 V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 15 mA
			–	1.0	V	I_{OL} = 5 mA, current into all pins > 60 mA
			–	0.4	V	I_{OL} = 5 mA, current into all pins ≤ 60 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -15 mA
			V_{DDP} - 1.0	–	V	I_{OH} = -5 mA, current from all pins > 60 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -5 mA, current from all pins ≤ 60 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on $\overline{\text{RESET}}$ pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode

Table 38 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			min.	max.		
Maximum current out of V_{SS}	I_{MVSS}	SR	–	120	mA	[3]
V_{DDP} = 3.3 V Range						
Output low voltage	V_{OL}	CC	–	1.0	V	I_{OL} = 8 mA
			–	0.4	V	I_{OL} = 2.5 mA
Output high voltage	V_{OH}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -8 mA
			V_{DDP} - 0.4	–	V	I_{OH} = -2.5 mA
Input low voltage on port pins (all except P0.0 & P0.1)	V_{ILP}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on P0.0 & P0.1	V_{ILP0}	SR	-0.2	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on RESET pin	V_{ILR}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input low voltage on TMS pin	V_{ILT}	SR	–	0.3 × V_{DDP}	V	CMOS Mode
Input high voltage on port pins (all except P0.0 & P0.1)	V_{IHP}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on P0.0 & P0.1	V_{IHP0}	SR	0.7 × V_{DDP}	V_{DDP}	V	CMOS Mode
Input high voltage on RESET pin	V_{IHR}	SR	0.7 × V_{DDP}	–	V	CMOS Mode
Input high voltage on TMS pin	V_{IHT}	SR	0.75 × V_{DDP}	–	V	CMOS Mode
Input Hysteresis	HYS	CC	0.03 × V_{DDP}	–	V	CMOS Mode[1]
Input Hysteresis on XTAL1	$HYSX$	CC	0.07 × V_{DDC}	–	V	[1]
Input low voltage at XTAL1	V_{ILX}	SR	V_{SS} - 0.5	0.3 × V_{DDC}	V	

4.2.3 ADC Characteristics

The values in the table below are given for an analog power supply between 4.5 V to 5.5 V. The ADC can be used with an analog power supply down to 3 V. But in this case, the analog parameters may show a reduced performance. All ground pins (V_{SS}) must be externally connected to one single star point in the system. The voltage difference between the ground pins must not exceed 200mV.

Table 40 ADC Characteristics (Operating Conditions apply; V_{DDP} = 5V Range)

Parameter	Symbol		Limit Values			Unit	Test Conditions/ Remarks
			min.	typ .	max.		
Analog reference voltage	V_{AREF}	SR	V_{AGND} + 1	V_{DDP}	V_{DDP} + 0.05	V	[1]
Analog reference ground	V_{AGND}	SR	V_{SS} - 0.05	V_{SS}	V_{AREF} - 1	V	[1]
Analog input voltage range	V_{AIN}	SR	V_{AGND}	–	V_{AREF}	V	
ADC clocks	f_{ADC}		–	24	25.8	MHz	module clock[1]
	f_{ADCI}		–	–	10	MHz	internal analog clock[1] See **Figure 35**
Sample time	t_S	CC	(2 + INPCR0.STC) × t_{ADCI}			µs	[1]
Conversion time	t_C	CC	See **Section 4.2.3.1**			µs	[1]
Total unadjusted error	|TUE|	CC	–	–	1	LSB	8-bit conversion[2]
			–	–	2	LSB	10-bit conversion[2]
Differential Nonlinearity	$\|EA_{DNL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Integral Nonlinearity	$\|EA_{INL}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Offset	$\|EA_{OFF}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Gain	$\|EA_{GAIN}\|$	CC	–	1	–	LSB	10-bit conversion[1]
Overload current coupling factor for analog inputs	K_{OVA}	CC	–	–	1.0 x 10^{-4}	–	$I_{OV} > 0$[1][3]
			–	–	1.5 x 10^{-3}	–	$I_{OV} < 0$[1][3]

Table 42 Power Down Current (Operating Conditions apply; V_{DDP} = 5V range)

Parameter	Symbol	Limit Values		Unit	Test Condition
		typ.[1]	max.[2]		
V_{DDP} = 5V Range					
Power-Down Mode	I_{PDP}	1	10	µA	T_A = + 25 °C[3][4]
		-	30	µA	T_A = + 85 °C[4][5]

1) The typical I_{PDP} values are measured at V_{DDP} = 5.0 V.

2) The maximum I_{PDP} values are measured at V_{DDP} = 5.5 V.

3) I_{PDP} has a maximum value of 200 µA at T_A = + 125 °C.

4) I_{PDP} is measured with: $\overline{\text{RESET}}$ = V_{DDP}, V_{AGND}= V_{SS}, RXD/INT0 = V_{DDP}; rest of the ports are programmed to be input with either internal pull devices enabled or driven externally to ensure no floating inputs.

5) Not subjected to production test, verified by design/characterization.

4.3 AC Parameters

The electrical characteristics of the AC Parameters are detailed in this section.

4.3.1 Testing Waveforms

The testing waveforms for rise/fall time, output delay and output high impedance are shown in **Figure 40**, **Figure 41** and **Figure 42**.

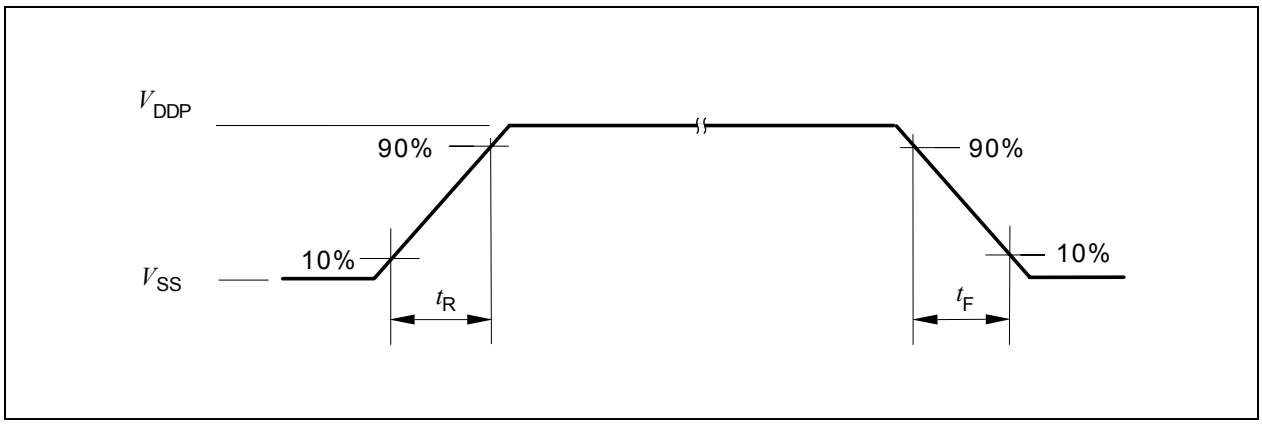


Figure 40 Rise/Fall Time Parameters

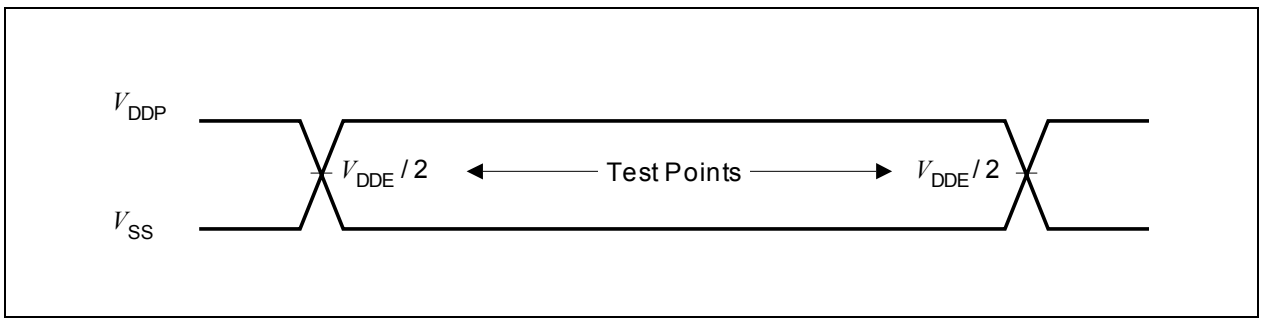


Figure 41 Testing Waveform, Output Delay

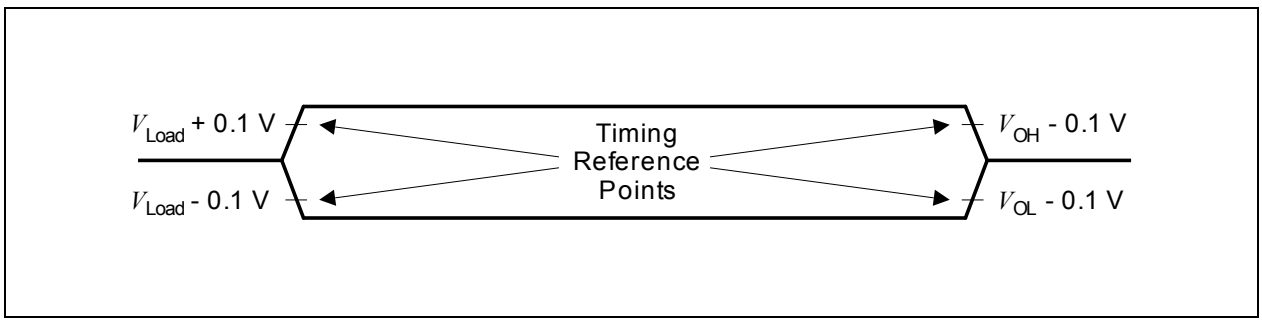


Figure 42 Testing Waveform, Output High Impedance

5.3 Quality Declaration

Table 2 shows the characteristics of the quality parameters in the XC886/888.

Table 2 Quality Parameters

Parameter	Symbol	Limit Values		Unit	Notes
		Min.	Max.		
ESD susceptibility according to Human Body Model (HBM)	V_{HBM}	-	2000	V	Conforming to EIA/JESD22-A114-B[1)]
ESD susceptibility according to Charged Device Model (CDM) pins	V_{CDM}	-	500	V	Conforming to JESD22-C101-C[1)]

1) Not all parameters are 100% tested, but are verified by design/characterization and test correlation.